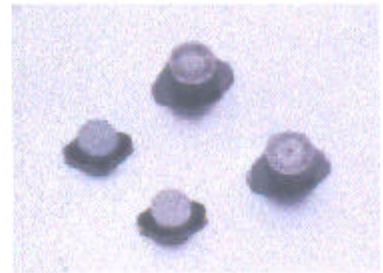


MINI-POT SMD INDUCTORS

FEATURES:

- * SUPERIOR QUALITY FROM AN AUTOMATED PRODUCTION LINE.
- * EXCELLENT COPLANDARITY.
- * LOW DCR, HIGH INDUCTANCE.
- * GOLD PLATED PADS WITH A SOLDERLESS WIRE WELDED TERMINATION.
- * PICK AND PLACE COMPATIBLE
- * TAPE AND REEL PACKAGING.
- * CLASS H MATERIALS (180 DEGREE C). CAN WITHSTAND STANDARD IR REFLOW.
- * IN HOUSE DESIGN IS AVAILABLE FOR CUSTOM REQUIREMENTS.



APPLICATIONS:

- * SIGNAL CONDITIONING.
- * DC-DC CONVERTORS.
- * PAGERS.
- * NOTEBOOK COMPUTERS.
- * NOTEBOOK COMPUTERS.
- * HYBRIDS.
- * CELLULAR TELEPHONES.
- * FILTERING.

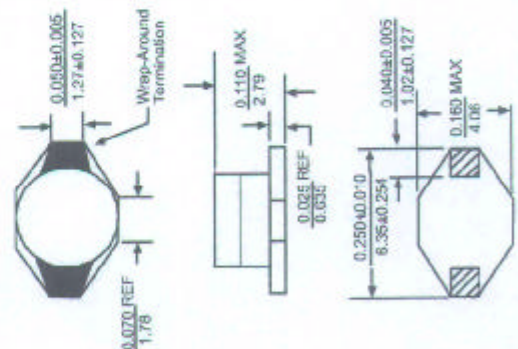
ELECTRICAL SPECIFICATIONS:

MODEL NO.	MIN. IND. (uH)	Q MIN	DCR MAX (OHM)	*RATED DC CURRENT (mA)
SMI-25-102	1000	50	4.00	10
SMI-25-152	1500	50	4.50	7
SMI-25-302	3000	60	11.20	7
SMI-25-502	5000	60	15.00	7
SMI-30-102	1000	40	1.00	10
SMI-30-152	1500	50	1.50	10
SMI-30-302	3000	50	3.80	7
SMI-30-502	5000	50	4.60	7
SMI-30-702	7000	50	5.10	7

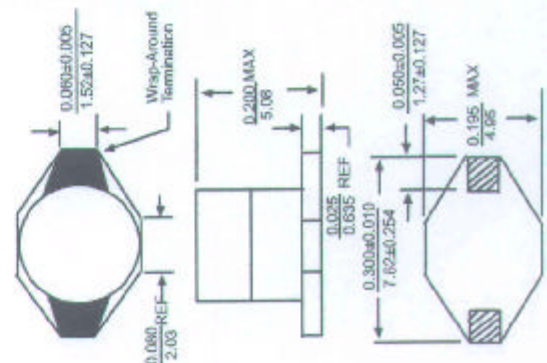
* RATED DC CURRENT IS BASED ON A 25% REDUCTION IN THE MINIMUM INDUCTANCE VALUE.

PHYSICAL DIMENSIONS: (UNIT: INCH/mm)

SMI-25-SERIES

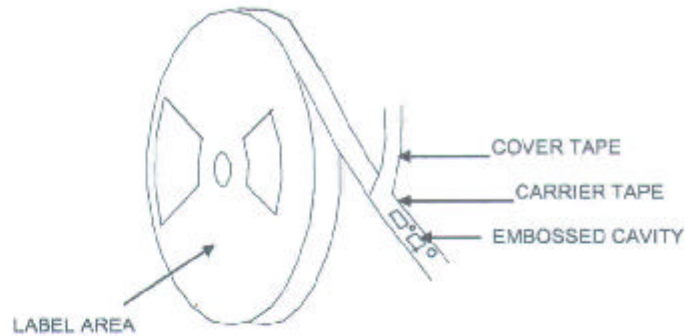
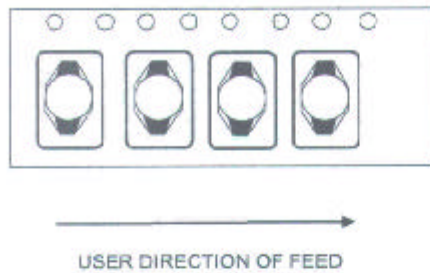


SMI-30-SERIES



PACKING

Tape and Reel Orientation



NOTE : Top view shown with cover tape removed.

MODEL	TYPE WIDTH	REEL WIDTH	COMPONENT PITCH	UNITS PER REEL
SMI-25 SERIES	12 mm	18.4 mm	8 mm	2500
SMI-30 SERIES	16 mm	22.4 mm	8mm	1000

TAPE SPECIFICATIONS:

Carrier Tape Type: Non-conductive.

Cover Tape Type: Non-antistatic.

Cover Tape Adhesion to Carrier: 60 -175 grams.

REEL SPECIFICATIONS:

Non-antistatic.

Diameter (flange) : 13" (330.2mm)

STANDARDS : All embossed carrier tape packaging will be accomplished in compliance with latest revision of EIA-481

"Taping of surface Mount Components for Automatic Placement".

ENVIRONMENTAL PERFORMANCE

ITEM	TEST	CONDITION
1	Thermal Shock	Ten cycles of 30 minutes @ -55°C, 15seconds maximum @room ambient, 30 minutes @ + 125°C, 15 seconds maximum @ room ambient.
2	Vibration	1 cycle of 30 minutes duratio per the following: 5-7 Hz constant displacement of .75 inch, 5 minutes, 7-30 Hz constant acceleration of 1.5 g' s, 10 minutes, 30-50 Hz constant displacement of 0.033 inch, 5 minutes, 50-500 Hz constant acceleration of 4.2 g' s, 10 minutes.
3	Solderability	Per MIL-STD-202, Method 208, except steam aging is omitted and pads are dipped 30 from vertical. Solder temperature: + 245°C ±5°C. Immersion dwell time: 5±1/2 seconds.
4	Storage Life	Subject the component to 168 hours at + 85°C and 85% relative humidity.
5	Moisture Resistance	Precondition at + 40°C for 60 minutes. Subject the component to 240 hours at + 40°C and 90 to 95% relative humidity.
6	Mechanical Shock	One-half sine pulse (8700 g' s for 0.3 milliseconds) in each direction along 3 mutually perpendicular axes in each direction (total of 6 shocks).